

ABSTRACT OF THE DISCLOSURE

In order to prevent forming bubbles on leads, in a solid-state image pickup apparatus provided with a solid-state image pickup element chip carrying solid-state image pickup elements electrically connected to leads on TAB tape, a protecting member for protecting the solid-state image pickup element chip, and a sealant for sealing them in the peripheral part of the solid-state image pickup element chip, each lead has an anchor hole formed in a portion in contact with the sealant.

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